C) Amendments to the Abstract:

Kindly amend the Abstract on page 18 of the original translation as indicated hereinafter as amended in marked up version.

To provide a A substrate temperature measurement apparatus and a processing apparatus, whereby thermocouple wire reliability is improved, influence of infrared ray rays on the chip is reduced and the temperature of the substrate can be accurately measured. It is provided with: a A chip (16) made of metal material reflecting infrared ray or rays and electromagnetic wave waves, having has an inserting insertion opening (16a) for inserting thermocouple wires (20a, 20b) which, is crushed and deformed with said the thermocouple wires inserted, and thereby united together with said the thermocouple wires, and contacted said with the substrate (13); and a supporting member or members (15b, 15c), made of material of lower thermal conductivity than said chip (16), are provided for supporting said chip (16).